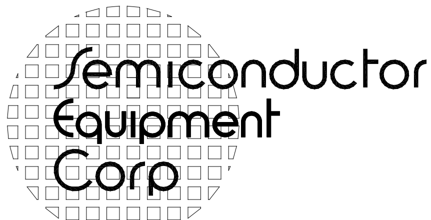


***Semiconductor Equipment Corporation***
*P.O. Box 8079, 5154 Goldman Ave*
*Moorpark, California 93020-8079*
*Phone: (805) 529-2293 Fax: (805) 529-2193*

# NEWS RELEASE

**FOR IMMEDIATE RELEASE**

**For more information contact:**

Lester Salvatierra / SEC Sales
Ph: 805-529-2293 Ext. 21
Fax: 805-529-2193
E-mail: seclester@aol.com
Website: www.Semicorp.com

## S.E.C. UPGRADES MODEL 860 BONDER TO NEW AND ENHANCED "EAGLE" BONDER

MOORPARK, California, U.S.A., January 22, 2007 – Semiconductor Equipment Corporation of Moorpark, California has upgraded its Model 860 Omni Bonder to the new Model 860 Eagle Bonder. An already well-established tool for R&D and low volume production in the optoelectronics, hybrid, MEMS, and medical device markets has been enhanced even further for applications including solder and gold bumped flip chip, eutectic bonding, thermosonic, and epoxy bonding.

New features include LED lighting for the viewer, CCD digital camera with enhanced resolution and magnification, 17" flat panel LCD color display, precision servo-driven Z motion with closed loop bond load control, real time graphic display of closed loop temperature controls for head, stage and spot heating. All new control software using Windows XP Pro operating system. The table is also new, with vibration isolation and a smaller footprint, but with a larger work area and more leg room.

These improvements distinguish the Model 860 Eagle bonder as a highly effective and versatile tool capable of performing the most demanding new bonding applications.

(Photo enclosed)

-30-